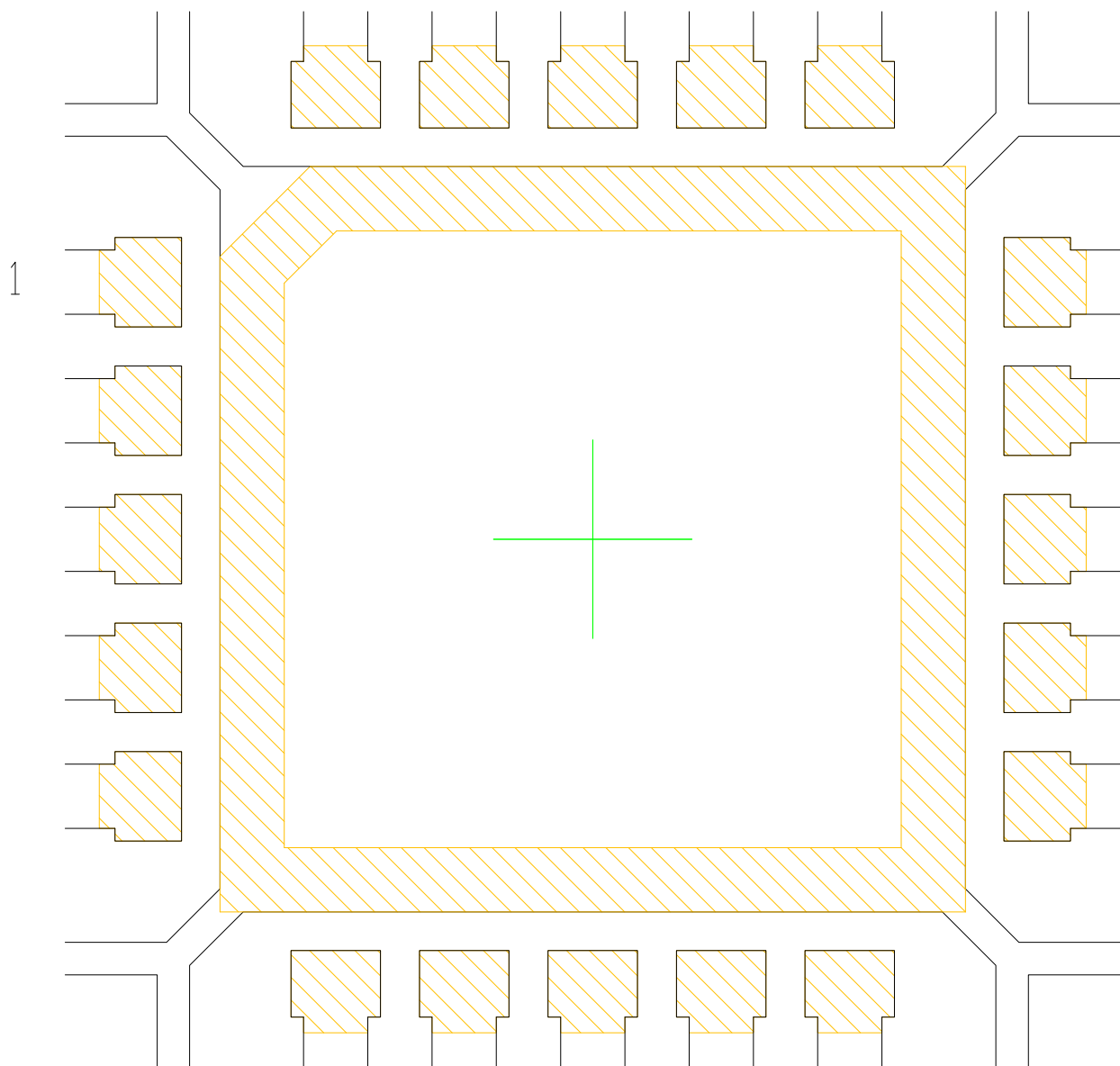



REVISIONS	
REV	DESCRIPTION
B	ADDED EXPOSED PAD SIZE AND LEADFRAME P/N



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 2.90 x 2.90 mm	
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 2.60 x 2.60 mm	TITLE QFN 20L 4x4 mm 0.50 PITCH BOND SHELL
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	LEADFRAME P/N: 235-00061 REV. 00
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	DO NOT SCALE
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	
		FILE NAME 20L-QFN-4X4-50P-BD.DWG